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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/654,232	09/03/2003	Stephen W. Bedell	YOR920030138US (16603)	4745
23389 75	90 05/06/2005		EXAMINER	
SCULLY SCOTT MURPHY & PRESSER, PC 400 GARDEN CITY PLAZA			HITESHEW, FELISA CARLA	
SUITE 300	CITY PLAZA		ART UNIT	PAPER NUMBER
GARDEN CIT	GARDEN CITY, NY 11530		1722	

DATE MAILED: 05/06/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

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	Application No.	Applicant(s)	
	10/654,232 BEDELL ET AL.		
Office Action Summary	Examiner	Art Unit	
	Felisa C. Hiteshew	1722	
The MAILING DATE of this communication app Period for Reply	pears on the cover sheet with the	correspondence address	
A SHORTENED STATUTORY PERIOD FOR REPL' THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.1 after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a reply - If NO period for reply is specified above, the maximum statutory period of Failure to reply within the set or extended period for reply will, by statute Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	36(a). In no event, however, may a reply be to within the statutory minimum of thirty (30) do will apply and will expire SIX (6) MONTHS from the application to become ABANDON	imely filed ays will be considered timely m the mailing date of this communication IED (35 U.S.C. § 133).	
Status			
1) Responsive to communication(s) filed on	_·		•
· <u> </u>	action is non-final.		
3) Since this application is in condition for allowar			
closed in accordance with the practice under E	Ex parte Quayle, 1935 C.D. 11, 4	453 O.G. 213.	
Disposition of Claims		1	
4) ☐ Claim(s) 1-24 is/are pending in the application 4a) Of the above claim(s) is/are withdray 5) ☐ Claim(s) is/are allowed. 6) ☐ Claim(s) 1-24 is/are rejected. 7) ☐ Claim(s) is/are objected to. 8) ☐ Claim(s) are subject to restriction and/o	wn from consideration.		
Application Papers			
9) The specification is objected to by the Examine 10) The drawing(s) filed on is/are: a) acc Applicant may not request that any objection to the Replacement drawing sheet(s) including the correct 11) The oath or declaration is objected to by the Examine 11.	epted or b) objected to by the drawing(s) be held in abeyance. Stion is required if the drawing(s) is o	ee 37 CFR 1.85(a). bjected to. See 37 CFR 1.121(d).
Priority under 35 U.S.C. § 119			
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority document 2. Certified copies of the priority document 3. Copies of the certified copies of the priority application from the International Bureau * See the attached detailed Office action for a list	s have been received. s have been received in Applica rity documents have been receiv u (PCT Rule 17.2(a)).	ition Noved in this National Stage	
Attachment(s)			
1) Notice of References Cited (PTO-892)	4) 🔲 Interview Summar	y (PTO-413)	

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Paper No(s)/Mail Date ____

U.S. Patent and Trademark Office PTOL-326 (Rev. 1-04)

2) Notice of Draftsperson's Patent Drawing Review (PTO-948)

3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)

Paper No(s)/Mail Date. _____.

5) Notice of Informal Patent Application (PTO-152)

6) Other: ____.

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Claim Rejections - 35 USC § 103

1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

- 2. The factual inquiries set forth in *Graham* v. *John Deere Co.*, 383 U.S. 1, 148 USPQ 459 (1966), that are applied for establishing a background for determining obviousness under 35 U.S.C. 103(a) are summarized as follows:
 - 1. Determining the scope and contents of the prior art.
 - 2. Ascertaining the differences between the prior art and the claims at issue.
 - 3. Resolving the level of ordinary skill in the pertinent art.
 - 4. Considering objective evidence present in the application indicating obviousness or nonobviousness.
- 3. This application currently names joint inventors. In considering patentability of the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of the various claims was commonly owned at the time any inventions covered therein were made absent any evidence to the contrary. Applicant is advised of the obligation under 37 CFR 1.56 to point out the inventor and invention dates of each claim that was not commonly owned at the time a later invention was made in order for the examiner to consider the applicability of 35 U.S.C. 103(c) and potential 35 U.S.C. 102(e), (f) or (g) prior art under 35 U.S.C. 103(a).
- 4. Claims 1-24 are rejected under 35 U.S.C. 103(a) as being unpatentable over Bendell, et al (U.S. Patent No. 6,841,457 B2).

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Bendell, et al '457 B2 teaches the use of hydrogen implantation to improve material properties of silicon-germanium-on-insulator material made by thermal diffusion, comprising a heterostructrue with a Si-containing substrate; an insulating region that is resistant to Ge diffusion present atop the Si-containing substrate; a substantially relaxed SiGe layer present atop the insulating region, wherein the substantially relaxed SiGe layer having a thickness of about 2000 nm or less (see column 4, lines 34-46 and abstract). A Si cap layer is formed atop a SiGe alloy layer which is formed on an unpatterned (3A) or patterned (3B) substrate (see column 4, lines 63-68). The SiGe alloy layer of the present invention may comprise SiGe alloys having up to 00.99 atomic percent Ge (when x is less than 1), as well as pure Ge (when x=0) that comprise 100 atomic percent Ge. It is preferred that the Ge content in the SiGe alloy layer be from about 0.1 to about 99.99 atomic percent with a Ge atomic percent of from about 10 to about 35 being even more highly preferred. The SiGe alloy is formed atop first single crystal Si layer (14) using a convention epitaxial growth method that is well-known. These method include low-pressure chemical vapor deposition (LPCVD). ultra-high vacuum chemical vapor deposition (UHVCVD), atomosphereic pressure chemical vapor deposition (APCVD), molecular beam epitaxy (MBE) and plasmaenhanced chemical vapor deposition (PECVD) (see column 6, lines 35-62). The optional cap layer employed in the present invention comprises any Si material including, but not limited to: epitaxial silicon (epi-Si), amorphous silicon (a:Si), single or polycrystalline Si or any combination thereof including multilayers (see column 7, lines 11-18). Specifically, the heating step of the present invention is an annealing step

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which is performed at a temperature of from about 900*C to about 1350*C, with a temperature of from about 1200* to about 1335*C, being more highly preferred.

Moreover, the heating step of the present invention is carried out in an oxidizing ambient which includes at least one oxygen-containing gas such as O2, NO, N2O, H2O 9steam), ozone, air and other like oxygen-containing gases. The oxygen-containing gas may be admixed with each other (such as an admixture or O2 an NO), or the gas may be diluted with an inert gas such as He, Ar, N2, Xe, Kr, or Ne (column 8, lines 42-52). To one of the initial structures containing the above top-down configuration, hydrogen ions were implanted into the structure at or near the interface between the barrier oxide and the 350 A Si layer using an ion dose of about 2.E16 H/cm. The implant was carrier out at an energy of about 67keV. The other structure was not subjected to this implant step (see column 10, lines 35-41).

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Felisa Hiteshew whose telephone number is (571) 272-1463. The examiner can normally be reached on Mondays through Thursdays from 4:30 AM to 3:00 PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Benjamin Utech, can be reached on (571) 272-1137. The fax phone number for the organization where this application or proceeding is assigned is (571) 273-1463.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information

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for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system. see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866- 217-9197 (toll-free).

FELISA HITESHEW

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